CRMGGL1003C

N-Channel 100V, 2.8mΩ Typ. Power MOSFET

Description

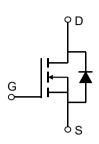
Features

• 100V, 150A

$$R_{DS(ON)}$$
 Typ = 2.8m Ω @ V_{GS} = 10 V

$$R_{DS(ON)}$$
 Typ = 3.4m Ω @ V_{GS} = 4.5V

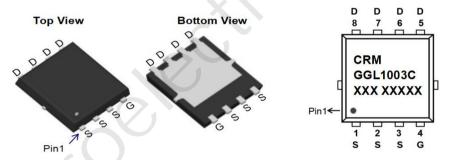
- Advanced Split Gate Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔVds TESTED!





Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMGGL1003C	CRMGGL1003C	PDFN5x6-8L	TAPING	13"	5000	60000

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		100	V
V_{GS}	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	T _C = 25°C	150	Α
I _D	Continuous Drain Current	T _C = 100°C 90	90	Α
I _{DM}	Pulsed Drain Current (1)		600	Α
E _{AS}	Single Pulsed Avalanche Energy (2)		333	mJ
P _D	Power Dissipation	T _C = 25°C	167	W
$R_{ heta JC}$	Thermal Resistance, Junction to Case		0.75	°C/W
T_J,T_STG	Junction & Storage Temperature Range		-55 to 150	°C

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Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Uni
Off Chara	acteristics					
V _{(BR)DSS}	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 100V, V _{GS} = 0V	-	-	1.0	μА
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics				6	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	1.5	2	V
D	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 10V, I_D = 30A$	-	2.8	3.6	mΩ
$R_{DS(ON)}$		$V_{GS} = 4.5V, I_{D} = 20A$	-	3.4	4.4	mΩ
Dynamic	Characteristics					
C _{iss}	Input Capacitance		-(5085	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 50V,$ f = 1MHz	X - \	1426	-	pF
C_{rss}	Reverse Transfer Capacitance			29	-	pF
Q_g	Total Gate Charge		U -	70	-	nC
Q_gs	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 50V, I_{D} = 30A$	-	12	-	nC
Q_{gd}	Gate Drain("Miller") Charge	VDS GGV, ID GG/V	-	15	-	nC
Switchin	g Characteristics					
$t_{\text{d(on)}}$	Turn-On DelayTime	<i>(</i>)	-	30	-	ns
t _r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 50V$	-	25	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	$I_D = 30A$, $R_{GEN} = 3\Omega$	-	50	-	ns
t_{f}	Turn-Off Fall Time		-	33	-	ns
Drain-So	urce Diode Characteristics and M	lax Ratings				
I _s	I _s Maximum Continuous Drain to Source Diode Forward Current			-	150	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	600	Α
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 30A$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I _F = 20A, di/dt = 100A/us	-	90	-	ns
Qrr	Body Diode Reverse Recovery Charge	i _F - 20A, ui/ul = 100A/uS	-	200	-	nC

Notes:

^{1.} Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

^{2.} E_{AS} condition: Starting T_J =25°C, V_{DD} =50V, V_G =10V, R_G =25ohm, L=0.5mH, I_{AS} =36.5A

^{3.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.

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Test Circuit

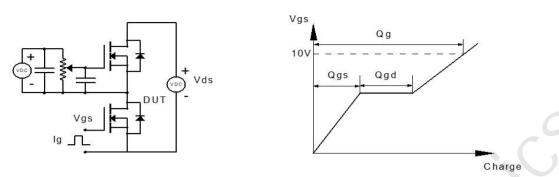


Figure 1: Gate Charge Test Circuit & Waveform

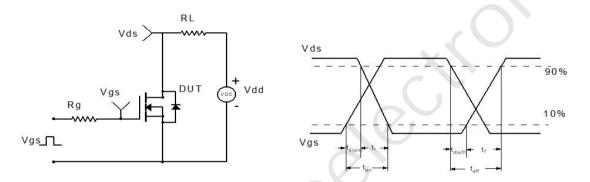


Figure 2: Resistive Switching Test Circuit & Waveform

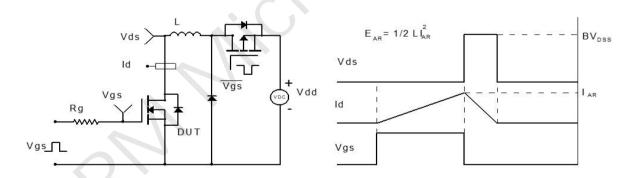


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

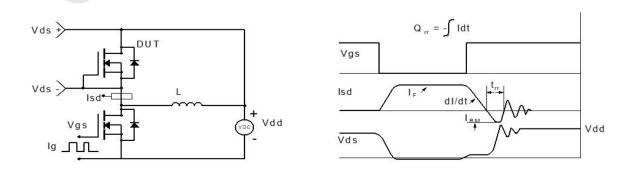
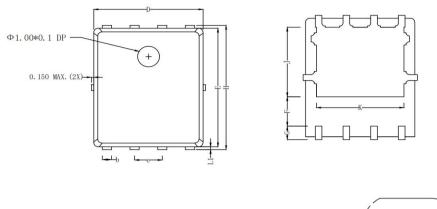
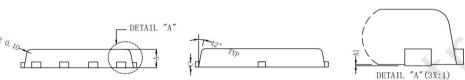


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(PDFN5x6-8L)





Symbol	MIN	TYP	MAX	
A	0.90	1.00	1.10	
A1	0.00	0.03	0.05	
b	0. 25	0.30	0.35	
C	0. 254 REF			
D	4.80	4.90	5. 00	
F	1.35 REF			
Е	5. 65	5. 75	5. 85	
е	1.27 BSC			
Н	5.90	6.00	6. 10	
L1	0.10	0.13	0.16	
G	0.55 REF			
K	4.00 REF			
J	3. 45 REF			

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Contact information

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